Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.1 EP)
Lead Count	16
Terminal Finish	NiPdAu

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.14E-02	83.25	832500	35.28	352824
Thermosets	Epoxy resin	Proprietary	1.40E-03	5.42	54200	2.30	22971
Thermosets	Phenol resin	Proprietary	8.89E-04	3.45	34500	1.46	14622
Other inorganic materials	Metal Hydroxide	Proprietary	1.40E-03	5.42	54200	2.30	22971
Others	Others	Proprietary	6.34E-04	2.46	24600	1.04	10426
Subtotal			2.58E-02	100.00	1000000	42.38	423813

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.93 E-02	97.50	975000	31.77	317716
Copper & its alloys	Iron	7439-89-6	4.65 E-04	2.35	23500	0.77	7658
Copper & its alloys	Zinc	7440-66-6	2.38 E-05	0.12	1200	0.04	391
Copper & its alloys	Phosphorus	7723-14-0	5.94 E-06	0.03	300	0.01	98
Subtotal			1.98 E-02	100.00	1000000	32.59	325863

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	7.96 E-05	90.9	909091	0.13	1309
Precious metals	Palladium	7440-05-3	5.97 E-06	6.8	68182	0.01	98
Precious metals	Gold	7440-57-5	1.99 E-06	2.3	22727	0.00	33
Subtotal			8.75 E-05	100.00	1000000	0.14	1440

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	4.47 E-05	99.99	1000000	0.07	735

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	1.08 E-02	100.0	1000000	17.78	177771

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.29 E-03	77.00	770000	5.42	54191
Other organic materials	Acrylic resin	Proprietary	2.99 E-04	7.00	70000	0.49	4926
Other organic materials	Acrylate	Proprietary	2.35 E-04	5.50	55000	0.39	3871
Other organic materials	Polybutadiene derivative	Proprietary	1.92 E-04	4.50	45000	0.32	3167
Thermoset	Epoxy resin	Proprietary	1.07 E-04	2.50	25000	0.18	1759
Other organic materials	Butadiene Copolymer	Proprietary	6.42 E-05	1.50	15000	0.11	1056
Others	Additive	Proprietary	6.42 E-05	1.50	15000	0.11	1056
Others	Peroxide	Proprietary	2.14 E-05	0.50	5000	0.04	352
Subtotal			4.28 E-03	100.0	1000000	7.04	70378

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.08 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.